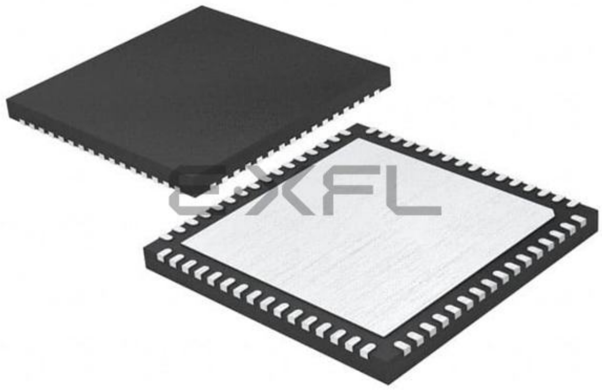

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc206-h-mr

FIGURE 2-7: INTERLEAVED PFC

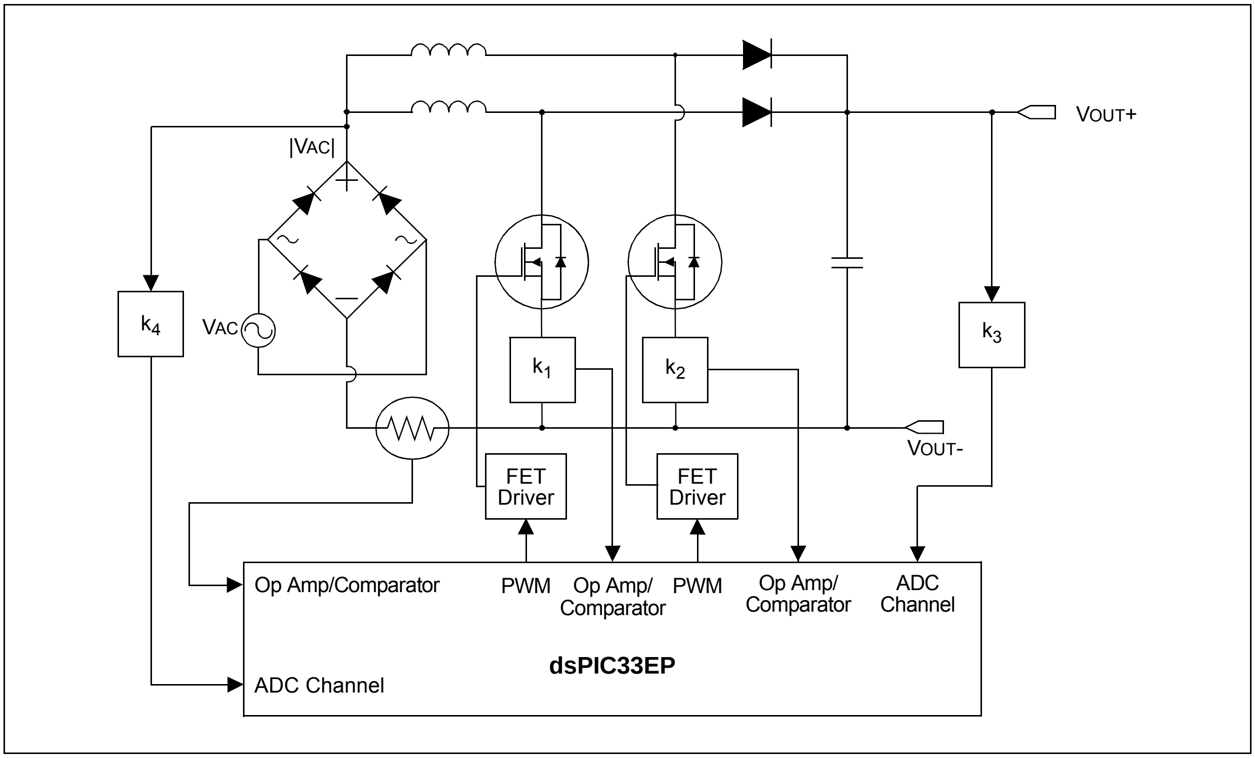


FIGURE 2-8: BEMF VOLTAGE MEASURED USING THE ADC MODULE

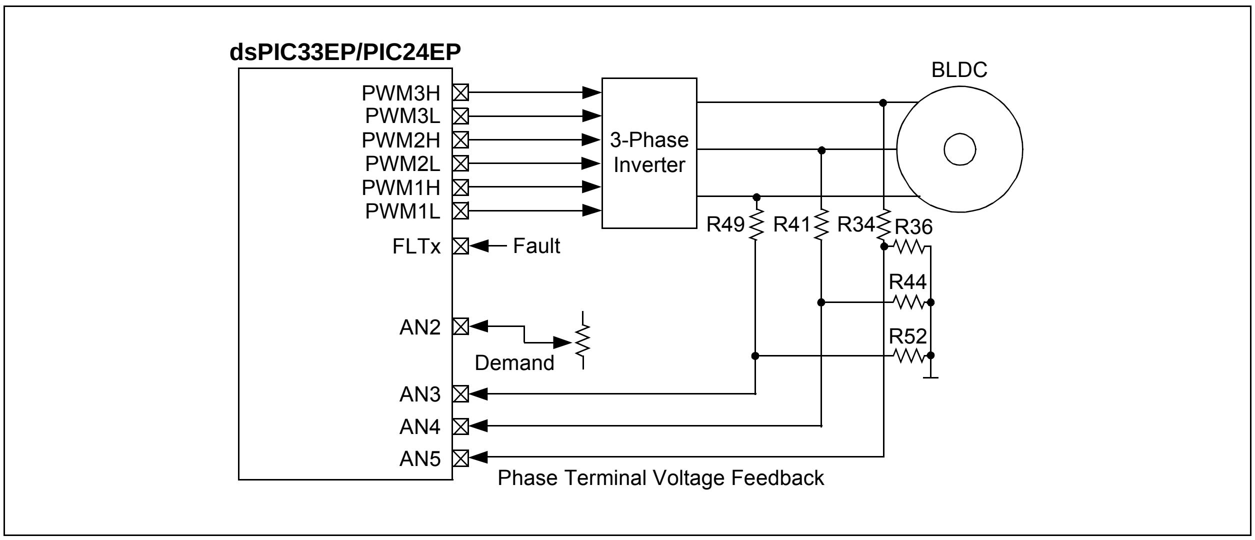
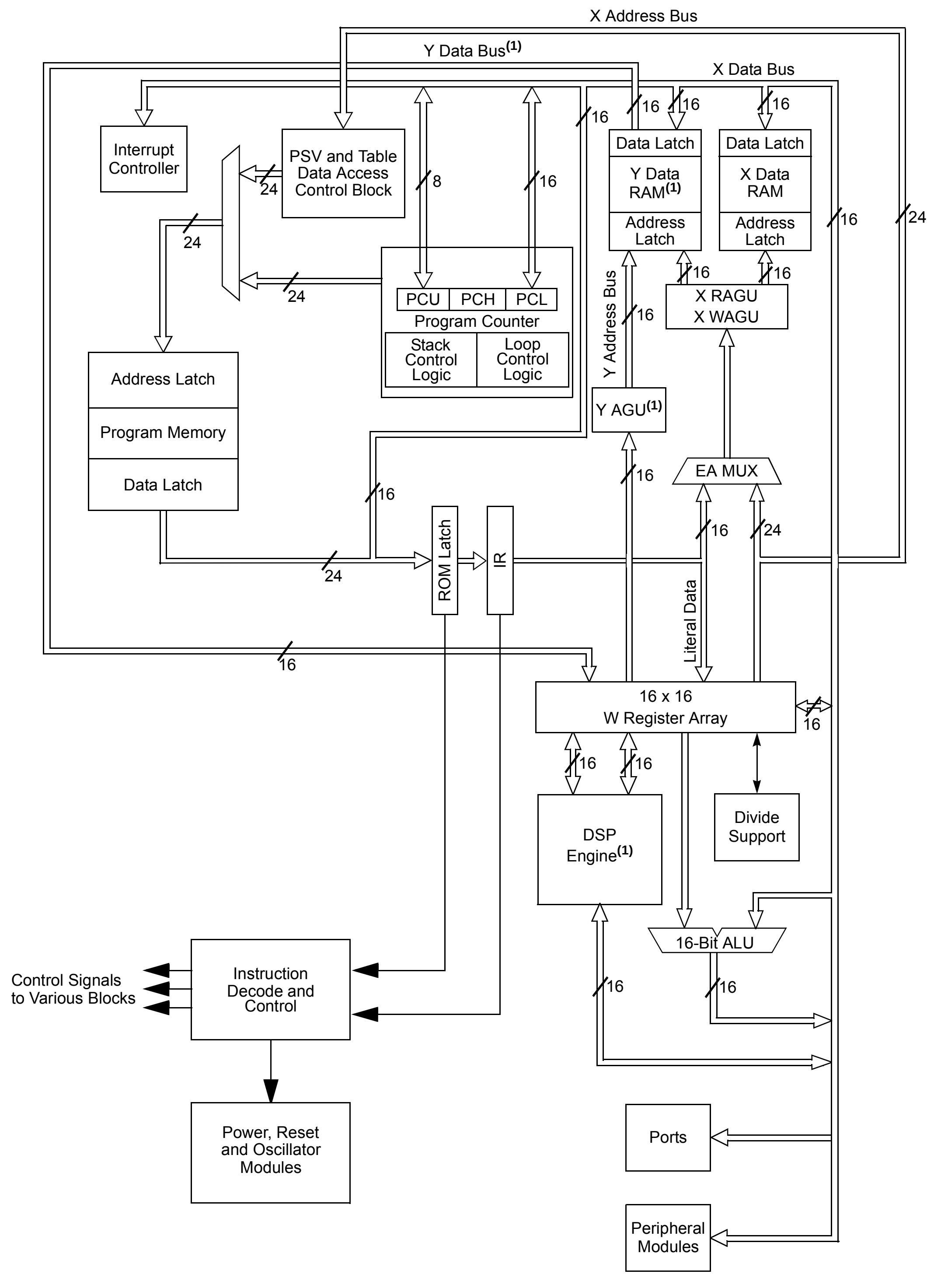
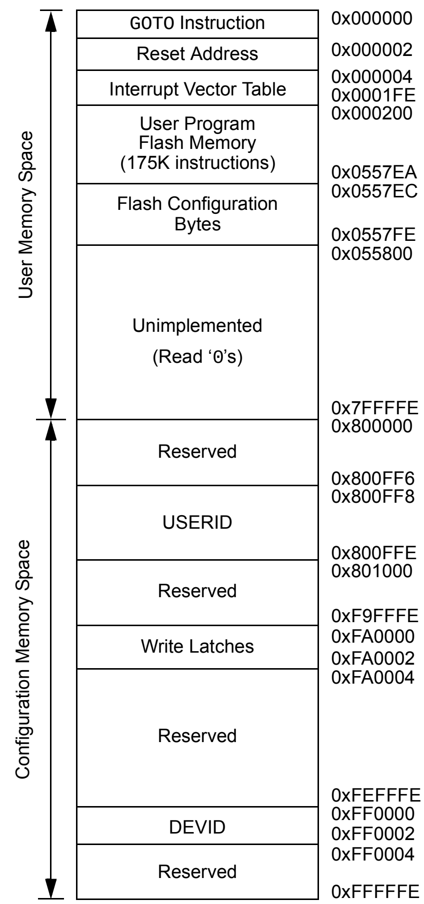


FIGURE 3-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X CPU BLOCK DIAGRAM



Note 1: This feature is not available on PIC24EPXXXGP/MC20X devices.

FIGURE 4-5: PROGRAM MEMORY MAP FOR dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X AND PIC24EP512GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

4.2 Data Address Space

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a separate 16-bit-wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps, which are presented by device family and memory size, are shown in Figure 4-7 through Figure 4-16.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a base Data Space address range of 64 Kbytes (32K words).

The base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space, which has a total address range of 16 Mbytes.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement up to 52 Kbytes of data memory (4 Kbytes of data memory for Special Function Registers and up to 48 Kbytes of data memory for RAM). If an EA points to a location outside of this area, an all-zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit-wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (`SE`) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (`ZE`) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using `MOV` instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an Address Pointer.

REGISTER 5-1: NVMCON: NONVOLATILE MEMORY (NVM) CONTROL REGISTER

R/SO-0(1)	R/W-0(1)	R/W-0(1)	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	NVMSIDL(2)	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0(1)
—	—	—	—	NVMOP3(3,4)	NVMOP2(3,4)	NVMOP1(3,4)	NVMOP0(3,4)
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit(1)
- 1 = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
- 0 = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit(1)
- 1 = Enables Flash program/erase operations
- 0 = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit(1)
- 1 = An improper program or erase sequence attempt or termination has occurred (bit is set automatically on any set attempt of the WR bit)
- 0 = The program or erase operation completed normally

bit 12 **NVMSIDL:** NVM Stop in Idle Control bit(2)
- 1 = Flash voltage regulator goes into Standby mode during Idle mode
- 0 = Flash voltage regulator is active during Idle mode

bit 11-4 **Unimplemented:** Read as ‘0’

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits(1,3,4)
- 1111 = Reserved
- 1110 = Reserved
- 1101 = Reserved
- 1100 = Reserved
- 1011 = Reserved
- 1010 = Reserved
- 0011 = Memory page erase operation
- 0010 = Reserved
- 0001 = Memory double-word program operation(5)
- 0000 = Reserved

Note 1: These bits can only be reset on a POR.
2: If this bit is set, there will be minimal power savings (IIDLE) and upon exiting Idle mode, there is a delay (TVREG) before Flash memory becomes operational.
3: All other combinations of NVMOP<3:0> are unimplemented.
4: Execution of the PWRSAV instruction is ignored while any of the NVM operations are in progress.
5: Two adjacent words on a 4-word boundary are programmed during execution of this operation.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
GIE	DISI	SWTRAP	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **GIE:** Global Interrupt Enable bit
1 = Interrupts and associated IE bits are enabled
0 = Interrupts are disabled, but traps are still enabled

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13 **SWTRAP:** Software Trap Status bit
1 = Software trap is enabled
0 = Software trap is disabled

bit 12-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 8-1: DMAxCON: DMA CHANNEL x CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
CHEN	SIZE	DIR	HALF	NULLW	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0
—	—	AMODE1	AMODE0	—	—	MODE1	MODE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CHEN:** DMA Channel Enable bit
1 = Channel is enabled
0 = Channel is disabled

bit 14 **SIZE:** DMA Data Transfer Size bit
1 = Byte
0 = Word

bit 13 **DIR:** DMA Transfer Direction bit (source/destination bus select)
1 = Reads from RAM address, writes to peripheral address
0 = Reads from peripheral address, writes to RAM address

bit 12 **HALF:** DMA Block Transfer Interrupt Select bit
1 = Initiates interrupt when half of the data has been moved
0 = Initiates interrupt when all of the data has been moved

bit 11 **NULLW:** Null Data Peripheral Write Mode Select bit
1 = Null data write to peripheral in addition to RAM write (DIR bit must also be clear)
0 = Normal operation

bit 10-6 **Unimplemented:** Read as ‘0’

bit 5-4 **AMODE<1:0>:** DMA Channel Addressing Mode Select bits
11 = Reserved
10 = Peripheral Indirect Addressing mode
01 = Register Indirect without Post-Increment mode
00 = Register Indirect with Post-Increment mode

bit 3-2 **Unimplemented:** Read as ‘0’

bit 1-0 **MODE<1:0>:** DMA Channel Operating Mode Select bits
11 = One-Shot, Ping-Pong modes are enabled (one block transfer from/to each DMA buffer)
10 = Continuous, Ping-Pong modes are enabled
01 = One-Shot, Ping-Pong modes are disabled
00 = Continuous, Ping-Pong modes are disabled

11.4 Peripheral Pin Select (PPS)

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. The challenge is even greater on low pin count devices. In an application where more than one peripheral needs to be assigned to a single pin, inconvenient workarounds in application code, or a complete redesign, may be the only option.

Peripheral Pin Select configuration provides an alternative to these choices by enabling peripheral set selection and their placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, users can better tailor the device to their entire application, rather than trimming the application to fit the device.

The Peripheral Pin Select configuration feature operates over a fixed subset of digital I/O pins. Users may independently map the input and/or output of most digital peripherals to any one of these I/O pins. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping once it has been established.

11.4.1 AVAILABLE PINS

The number of available pins is dependent on the particular device and its pin count. Pins that support the Peripheral Pin Select feature include the label, “RPn” or “RPIn”, in their full pin designation, where “n” is the remappable pin number. “RP” is used to designate pins that support both remappable input and output functions, while “RPI” indicates pins that support remappable input functions only.

11.4.2 AVAILABLE PERIPHERALS

The peripherals managed by the Peripheral Pin Select are all digital-only peripherals. These include general serial communications (UART and SPI), general purpose timer clock inputs, timer-related peripherals (input capture and output compare) and interrupt-on-change inputs.

In comparison, some digital-only peripheral modules are never included in the Peripheral Pin Select feature. This is because the peripheral’s function requires special I/O circuitry on a specific port and cannot be easily connected to multiple pins. These modules include I^2C™ and the PWM. A similar requirement excludes all modules with analog inputs, such as the ADC Converter.

A key difference between remappable and non-remappable peripherals is that remappable peripherals are not associated with a default I/O pin. The peripheral must always be assigned to a specific I/O pin before it can be used. In contrast, non-remappable peripherals are always available on a default pin, assuming that the peripheral is active and not conflicting with another peripheral.

When a remappable peripheral is active on a given I/O pin, it takes priority over all other digital I/O and digital communication peripherals associated with the pin. Priority is given regardless of the type of peripheral that is mapped. Remappable peripherals never take priority over any analog functions associated with the pin.

11.4.3 CONTROLLING PERIPHERAL PIN SELECT

Peripheral Pin Select features are controlled through two sets of SFRs: one to map peripheral inputs and one to map outputs. Because they are separately controlled, a particular peripheral’s input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

The association of a peripheral to a peripheral-selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

REGISTER 11-20: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTER 2

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP39R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP38R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP39R<5:0>:** Peripheral Output Function is Assigned to RP39 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP38R<5:0>:** Peripheral Output Function is Assigned to RP38 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-21: RPOR3: PERIPHERAL PIN SELECT OUTPUT REGISTER 3

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP41R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP40R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP41R<5:0>:** Peripheral Output Function is Assigned to RP41 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP40R<5:0>:** Peripheral Output Function is Assigned to RP40 Output Pin bits (see Table 11-3 for peripheral function numbers)

12.0 TIMER1

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

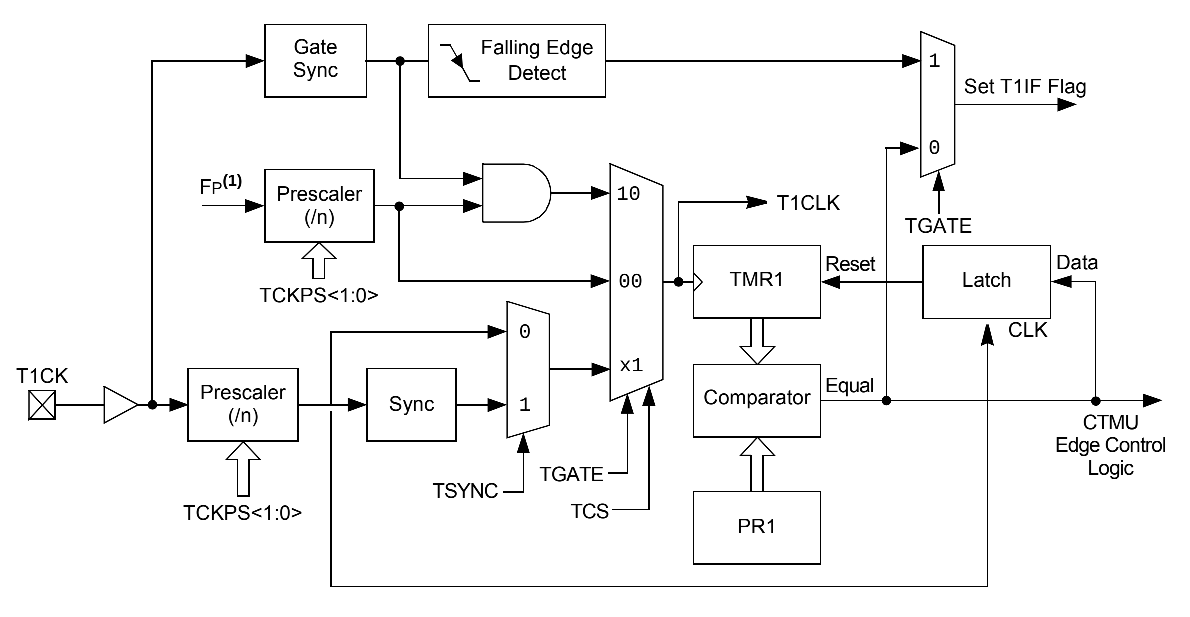
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

REGISTER 16-7: PWMCONx: PWMx CONTROL REGISTER (CONTINUED)

bit 7-6	**DTC<1:0>:** Dead-Time Control bits 11 = Dead-Time Compensation mode 10 = Dead-time function is disabled 01 = Negative dead time is actively applied for Complementary Output mode 00 = Positive dead time is actively applied for all output modes
bit 5	**DTCP:** Dead-Time Compensation Polarity bit(3) When Set to '1': If DTCMPx = 0, PWMxL is shortened and PWMxH is lengthened. If DTCMPx = 1, PWMxH is shortened and PWMxL is lengthened. When Set to '0': If DTCMPx = 0, PWMxH is shortened and PWMxL is lengthened. If DTCMPx = 1, PWMxL is shortened and PWMxH is lengthened.
bit 4	**Unimplemented:** Read as '0'
bit 3	**MTBS:** Master Time Base Select bit 1 = PWM generator uses the secondary master time base for synchronization and as the clock source for the PWM generation logic (if secondary time base is available) 0 = PWM generator uses the primary master time base for synchronization and as the clock source for the PWM generation logic
bit 2	**CAM:** Center-Aligned Mode Enable bit(2,4) 1 = Center-Aligned mode is enabled 0 = Edge-Aligned mode is enabled
bit 1	**XPRES:** External PWMx Reset Control bit(5) 1 = Current-limit source resets the time base for this PWM generator if it is in Independent Time Base mode 0 = External pins do not affect PWMx time base
bit 0	**IUE:** Immediate Update Enable bit(2) 1 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are immediate 0 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are synchronized to the PWMx period boundary

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; otherwise, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be '1' and the CLMOD bit in the FCLCONx register must be '0'.

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Serial Peripheral Interface (SPI)"** (DS70569) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with Motorola® SPI and SIOP interfaces.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device family offers two SPI modules on a single device. These modules, which are designated as SPI1 and SPI2, are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

> **Note:** In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of the SPI2 module, but results in a lower maximum speed for SPI2. See **Section 30.0 "Electrical Characteristics"** for more information.

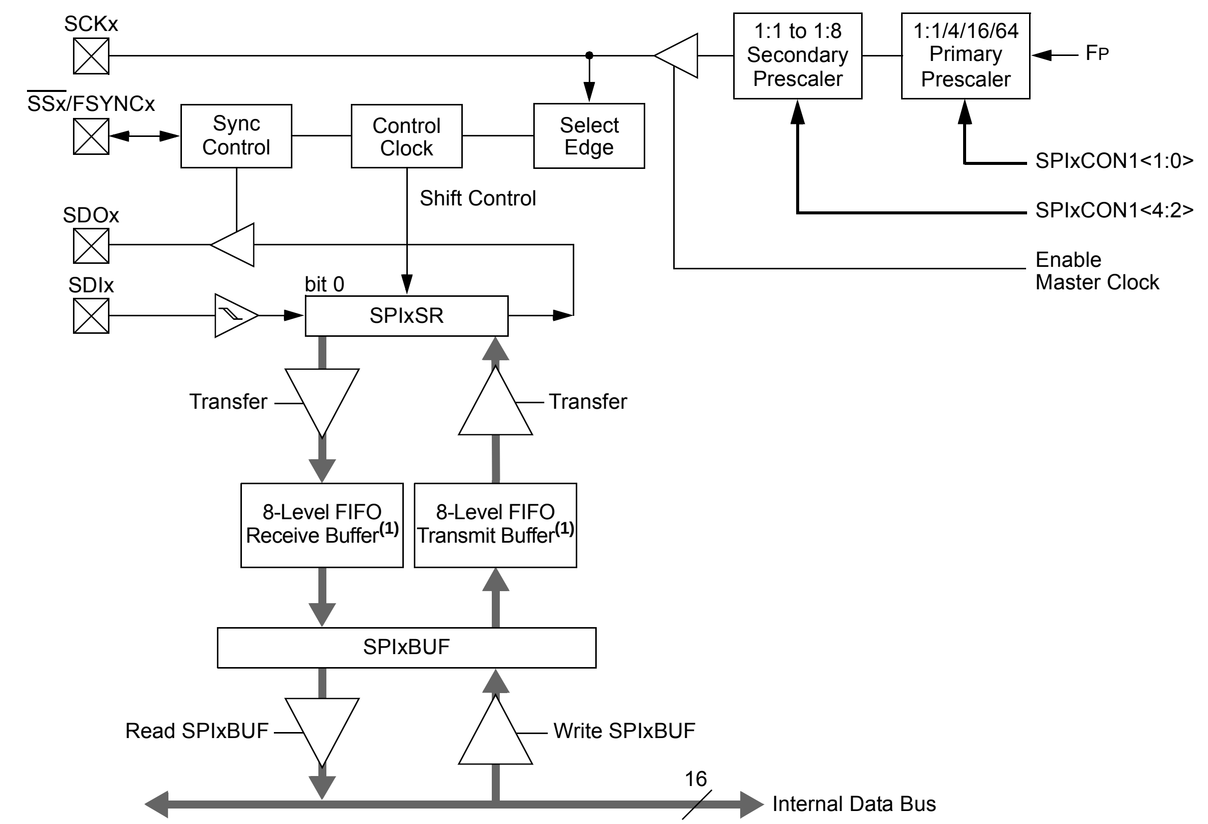
The SPIx serial interface consists of four pins, as follows:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- $\overline{\text{SSx}}$/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, $\overline{\text{SSx}}$ is not used. In 2-pin mode, neither SDOx nor $\overline{\text{SSx}}$ is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

FIGURE 18-1: SPIx MODULE BLOCK DIAGRAM



Note 1: In Standard mode, the FIFO is only one level deep.

NOTES:

REGISTER 24-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER[1,2] (CONTINUED)

bit 4	**OC1CS:** Clock Source for OC1 bit 1 = Generates clock pulse when the broadcast command is executed 0 = Does not generate clock pulse when the broadcast command is executed
bit 3	**OC4TSS:** Trigger/Synchronization Source for OC4 bit 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed
bit 2	**OC3TSS:** Trigger/Synchronization Source for OC3 bit 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed
bit 1	**OC2TSS:** Trigger/Synchronization Source for OC2 bit 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed
bit 0	**OC1TSS:** Trigger/Synchronization Source for OC1 bit 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

2: This register is only used with the PTGCTRL OPTION = 1111 Step command.

25.1.2 OP AMP CONFIGURATION B

Figure 25-7 shows a typical inverting amplifier circuit with the output of the op amp (OAxOUT) externally routed to a separate analog input pin (ANy) on the device. This op amp configuration is slightly different in terms of the op amp output and the ADC input connection, therefore, RINT1 is not included in the transfer function. However, this configuration requires the designer to externally route the op amp output (OAxOUT) to another analog input pin (ANy). See Table 30-53 in **Section 30.0 "Electrical Characteristics"** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 "Electrical Characteristics"** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration.

Figure 25-7 also defines the equation to be used to calculate the expected voltage at point VOAxOUT. This is the typical inverting amplifier equation.

25.2 Op Amp/Comparator Resources

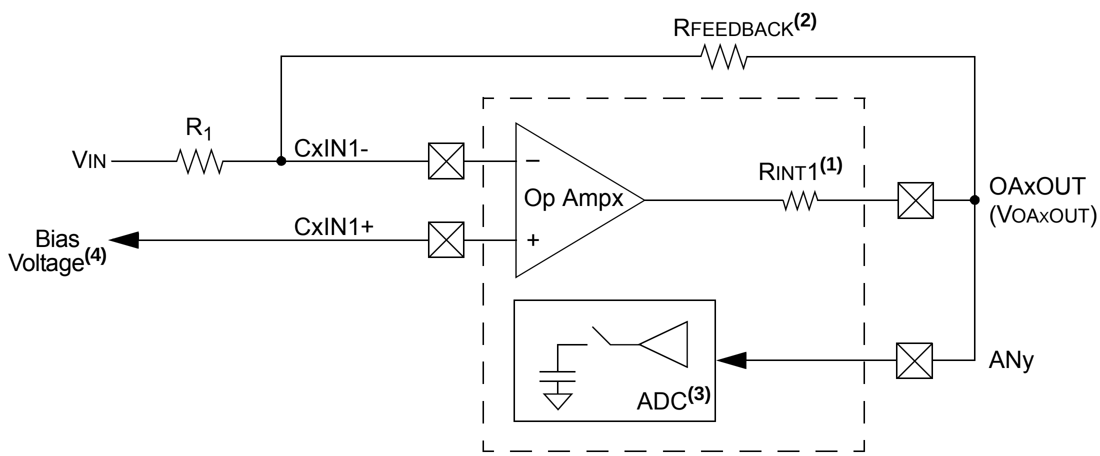
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

25.2.1 KEY RESOURCES

- **"Op Amp/Comparator"** (DS70357) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 25-7: OP AMP CONFIGURATION B



$$V_{OAxOUT} = \left(\frac{R_{FEEDBACK}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

Note 1: See Table 30-53 for the Typical value.
2: See Table 30-53 for the Minimum value for the feedback resistor.
3: See Table 30-60 and Table 30-61 for the minimum sample time (TSAMP).
4: CVREF1O or CVREF2O are two options that are available for supplying bias voltage to the op amps.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔIWDT)[1]

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔIWDT current is the additional current consumed when the module is enabled. This current should be added to the base IPD current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (IDOZE)[1]							
DC73a[2]	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a[2]	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a[2]	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a[2]	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current[1,2]**					
DI50		I/O Pins 5V Tolerant[3]	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

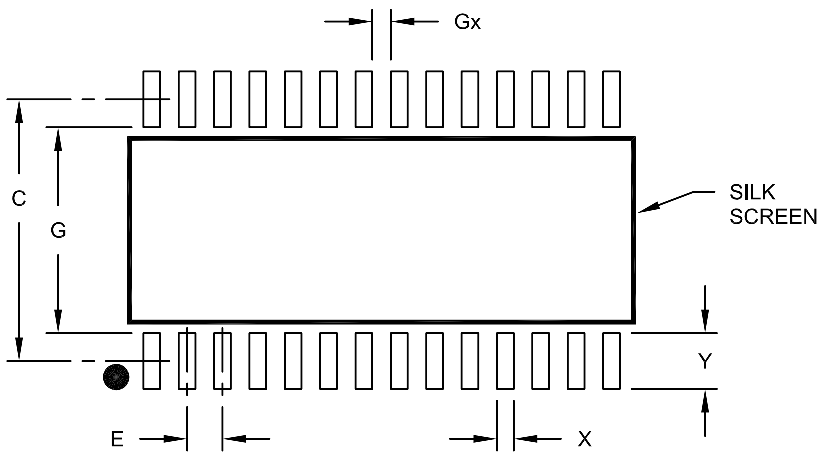
6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

TABLE A-5: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	• Throughout: qualifies all footnotes relating to the operation of analog modules below V_{DDMIN} (replaces "will have" with "may have") • Throughout: changes all references of SPI timing parameter symbol "TscP" to "FscP" • Table 30-1: changes V_{DD} range to 3.0V to 3.6V • Table 30-4: removes Parameter DC12 (RAM Retention Voltage) • Table 30-7: updates Maximum values at 10 and 20 MIPS • Table 30-8: adds Maximum I_{PD} values, and removes all ΔI_{WDT} entries • Adds new Table 30-9 (Watchdog Timer Delta Current) with consolidated values removed from Table 30-8. All subsequent tables are renumbered accordingly. • Table 30-10: adds footnote for all parameters for 1:2 Doze ratio • Table 30-11: - changes Minimum and Maximum values for D120 and D130 - adds Minimum and Maximum values for D131 - adds Minimum and Maximum values for D150 through D156, and removes Typical values • Table 30-12: - reformats table for readability - changes I_{OL} conditions for DO10 • Table 30-14: adds footnote to D135 • Table 30-17: changes Minimum and Maximum values for OS30 • Table 30-19: - splits temperature range and adds new values for F20a - reduces temperature range for F20b to extended temperatures only • Table 30-20: - splits temperature range and adds new values for F21a - reduces temperature range for F20b to extended temperatures only • Table 30-53: - adds Maximum value to CM30 - adds footnote ("Parameter characterized...") to multiple parameters • Table 30-55: adds Minimum and Maximum values for all CTMUI specifications, and removes Typical values • Table 30-57: adds new footnote to AD09 • Table 30-58: - removes all specifications for accuracy with external voltage references - removes Typical values for AD23a and AD24a - replaces Minimum and Maximum values for AD21a, AD22a, AD23a and AD24a with new values, split by Industrial and Extended temperatures - removes Maximum value of AD30 - removes Minimum values from AD31a and AD32a - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-59: - removes all specifications for accuracy with external voltage references - removes Maximum value of AD30 - removes Typical values for AD23b and AD24b - replaces Minimum and Maximum values for AD21b, AD22b, AD23b and AD24b with new values, split by Industrial and Extended temperatures - removes Minimum and Maximum values from AD31b, AD32b, AD33b and AD34b - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-61: Adds footnote to AD51
Section 32.0 "DC and AC Device Characteristics Graphs"	• Updates Figure 32-6 (Typical I_{DD} @ 3.3V) with individual current vs. processor speed curves for the different program memory sizes
Section 33.0 "Packaging Information"	• Replaces drawing C04-149C (64-pin QFN, 7.15 x 7.15 exposed pad) with C04-154A (64-pin QFN, 5.4 x 5.4 exposed pad)